Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: OA / SN / SM (C2X) 008 SOIC .150in.(3.90mm) matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
	1	"Contained In"	% I otal	I		62.24	(mg) Total	Mold Compound	% ot Total Weight	79.8
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm		, ,,	•	·	1
Silica, vitreous	60676-86-0	Mold Compound	69.354	54.096	693,542		Silica, vitreous	60676-86-0	86.91	
Epoxy Resin	Trade Secret	Mold Compound	6.121	4.774	61,207		Epoxy Resin	Trade Secret	7.67	
Phenolic Resin	Trade Secret	Mold Compound	4.078	3.181	40,778		Phenolic Resin	Trade Secret	5.11	
Carbon Black	1333-86-4	Mold Compound	0.247	0.193	2,474		Carbon Black	1333-86-4	0.31	<u>l</u>
Copper	7440-50-8	Lead Frame	10.031	7.825	100,314			Total		
Iron	7439-89-6	Lead Frame	0.247	0.192	2,468	8.19	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	0.156	2,000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.010	131		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.007	87		Silver	7440-22-4	1.91	
Silver (Ag)	7440-22-4	Die Attach	0.563	0.439	5,625		Zinc	7440-66-6	0.13	
Modified Epoxy Resin	13561-08-5	Die Attach	0.105	0.082	1,050		Phosphorous	7723-14-0	0.08	
Diglycidylether of bisphenol-F	54208-63-8	Die Attach	0.056	0.044	563			Total		
4-Methyl-2-phenyl-1H-imidazole	827-43-0	Die Attach	0.026	0.020	263	0.59	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	5.850	75,000		Silver (Ag)	7440-22-4	75.00	
Copper	7440-50-8	Wire Bond palladium coated copper (CuPd)	0.197	0.153	1,965		Modified Epoxy Resin	13561-08-5	14.00	
Palladium	7440-05-3	Wire Bond palladium coated copper (CuPd)	0.004	0.003	35		iglycidylether of bisphenol-F	54208-63-8	7.50	
Tin	7440-31-5 Pi	ating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	0.975	12,500	4-M	ethyl-2-phenyl-1H-imidazole	827-43-0	3.50]
		TOTALS:	100.000	78.000	1,000,000			Total		
	omply with EU Directives: 2003	TOTALS: Total Mass 2/95/EC (27 January 2003) & Directive 2011/65/EU (08 J				5.85	Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3	100.00 % of Total Weight 100.00	7.5
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